

**Technische Information / technical information****eupec**IGBT-Module  
IGBT-Modules**FS10R06XL4**vorläufige Daten  
preliminary data**Höchstzulässige Werte / maximum rated values****Elektrische Eigenschaften / electrical properties**

Kollektor Emitter Sperrspannung collector emitter voltage	$T_{vj} = 25\text{ °C}$	$V_{CES}$	600	V
Kollektor Dauergleichstrom DC collector current	$T_C = 80\text{ °C}$ $T_C = 25\text{ °C}$	$I_{C,nom.}$ $I_C$	10 17	A A
Periodischer Kollektor Spitzenstrom repetitive peak collector current	$t_p = 1\text{ ms}, T_C = 80\text{ °C}$	$I_{CRM}$	20	A
Gesamt Verlustleistung total power dissipation	$T_c = 25\text{ °C}, \text{ Transistor}$	$P_{tot}$	76	W
Gate Emitter Spitzenspannung gate emitter peak voltage		$V_{GES}$	$\pm 20$	V
Dauergleichstrom DC forward current		$I_F$	10	A
Periodischer Spitzenstrom repetitive peak forward current	$t_p = 1\text{ ms}$	$I_{FRM}$	20	A
Grenzlastintegral $I^2t$ value	$V_R = 0\text{ V}, t_p = 10\text{ ms}, T_{vj} = 125\text{ °C}$	$I^2t$	12	A <sup>2</sup> s
Isolations Prüfspannung insulation test voltage	RMS, f= 50Hz, t= 1min	$V_{ISOL}$	2,5	kV

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**Charakteristische Werte / characteristic values****Transistor Wechselrichter / transistor inverter**

			min.	typ.	max.	
Kollektor Emitter Sättigungsspannung collector emitter saturation voltage	$V_{GE} = 15\text{ V}, T_{vj} = 25\text{ °C}, I_C = I_{C,nom}$	$V_{CESat}$	-	1,95	2,55	V
	$V_{GE} = 15\text{ V}, T_{vj} = 125\text{ °C}, I_C = I_{C,nom}$		-	2,20	-	V
Gate Schwellenspannung gate threshold voltage	$V_{CE} = V_{GE}, T_{vj} = 25\text{ °C}, I_C = 0,4\text{ mA}$	$V_{GE(th)}$	4,5	5,5	6,5	V
Gateladung gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$	$Q_G$	-	0,05	-	$\mu\text{C}$
Eingangskapazität input capacitance	f= 1MHz, $T_{vj} = 25\text{ °C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$	$C_{ies}$	-	0,45	-	nF
Rückwirkungskapazität reverse transfer capacitance	f= 1MHz, $T_{vj} = 25\text{ °C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$	$C_{res}$	-	0,04	-	nF
Kollektor Emitter Reststrom collector emitter cut off current	$V_{CE} = 600\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25\text{ °C}$	$I_{CES}$	-	-	5	mA
Gate Emitter Reststrom gate emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25\text{ °C}$	$I_{GES}$	-	-	400	nA

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## Charakteristische Werte / characteristic values

## Transistor Wechselrichter / transistor inverter

			min.	typ.	max.	
Einschaltverzögerungszeit (induktive Last) turn on delay time (inductive load)	$I_C = 10 \text{ A}, V_{CC} = 300 \text{ V}$	$t_{d,on}$	-	20	-	ns
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 25^\circ \text{C}$					
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 125^\circ \text{C}$			21		ns
Anstiegszeit (induktive Last) rise time (inductive load)	$I_C = 10 \text{ A}, V_{CC} = 300 \text{ V}$	$t_r$	-	7	-	ns
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 25^\circ \text{C}$					
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 125^\circ \text{C}$			8		ns
Abschaltverzögerungszeit (induktive Last) turn off delay time (inductive load)	$I_C = 10 \text{ A}, V_{CC} = 300 \text{ V}$	$t_{d,off}$	-	80	-	ns
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 25^\circ \text{C}$					
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 125^\circ \text{C}$			110		ns
Fallzeit (induktive Last) fall time (inductive load)	$I_C = 10 \text{ A}, V_{CC} = 300 \text{ V}$	$t_f$	-	18	-	ns
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 25^\circ \text{C}$					
	$V_{GE} = \pm 15 \text{ V}, R_G = 27 \ \Omega, T_{vj} = 125^\circ \text{C}$			25		ns
Einschaltverlustenergie pro Puls turn on energy loss per pulse	$I_C = 10 \text{ A}, V_{CC} = 300 \text{ V}$ $R_G = 27 \ \Omega, T_{vj} = 125^\circ \text{C}, L_G = 25 \text{ nH}$	$E_{on}$	-	0,25	-	mJ
Ausschaltverlustenergie pro Puls turn off energy loss per pulse	$I_C = 10 \text{ A}, V_{CC} = 300 \text{ V}$ $R_G = 27 \ \Omega, T_{vj} = 125^\circ \text{C}, L_G = 25 \text{ nH}$	$E_{off}$	-	0,30	-	mJ
Kurzschlussverhalten SC data	$t_P \leq 10 \mu\text{sec}, V_{GE} \leq 15 \text{ V}, T_{vj} = 125^\circ \text{C},$ $V_{CC} = 360 \text{ V}, V_{CEmax} = V_{CEs} - L_{\sigma CE} \cdot  di/dt $	$I_{SC}$	-	40	-	A
Modulinduktivität stray inductance module		$L_{\sigma CE}$	-	25	-	nH
Leitungswiderstand, Anschluss-Chip lead resistance, terminal-chip	$T_c = 25^\circ \text{C}$	$R_{CC/EE}$	-	8	-	m $\Omega$

## Charakteristische Werte / characteristic values

## Diode Wechselrichter / diode inverter

Durchlassspannung forward voltage	$I_F = 10 \text{ A}, V_{GE} = 0 \text{ V}, T_{vj} = 25^\circ \text{C}$	$V_F$	-	1,85	2,25	V
	$I_F = 10 \text{ A}, V_{GE} = 0 \text{ V}, T_{vj} = 125^\circ \text{C}$					
Rückstromspitze peak reverse recovery current	$I_F = 10 \text{ A}, -di_F/dt = 1500 \text{ A}/\mu\text{s}$	$I_{RM}$	-	26	-	A
	$V_R = 300 \text{ V}, V_{GE} = -10 \text{ V}, T_{vj} = 25^\circ \text{C}$					
	$V_R = 300 \text{ V}, V_{GE} = -10 \text{ V}, T_{vj} = 125^\circ \text{C}$			27		A
Sperrverzögerungsladung recovered charge	$I_F = 10 \text{ A}, -di_F/dt = 1500 \text{ A}/\mu\text{s}$	$Q_r$	-	0,55	-	$\mu\text{C}$
	$V_R = 300 \text{ V}, V_{GE} = -10 \text{ V}, T_{vj} = 25^\circ \text{C}$					
	$V_R = 300 \text{ V}, V_{GE} = -10 \text{ V}, T_{vj} = 125^\circ \text{C}$			0,95		$\mu\text{C}$
Ausschaltenergie pro Puls reverse recovery energy	$I_F = 10 \text{ A}, -di_F/dt = 1500 \text{ A}/\mu\text{s}$	$E_{rec}$	-	0,15	-	mJ
	$V_R = 300 \text{ V}, V_{GE} = -10 \text{ V}, T_{vj} = 25^\circ \text{C}$					
	$V_R = 300 \text{ V}, V_{GE} = -10 \text{ V}, T_{vj} = 125^\circ \text{C}$			0,2		mJ

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## Charakteristische Werte / characteristic values

## NTC-Widerstand / NTC-thermistor

			min.	typ.	max.	
Nennwiderstand rated resistance	$T_c = 25^\circ\text{C}$	$R_{25}$	-	5	-	k $\Omega$
Abweichung von $R_{100}$ deviation of $R_{100}$	$T_c = 100^\circ\text{C}$ , $R_{100} = 493\Omega$	$\Delta R/R$	-5	-	5	%
Verlustleistung power dissipation	$T_c = 25^\circ\text{C}$	$P_{25}$	-	-	20	mW
B-Wert B-value	$R_2 = R_1 \exp[B(1/T_2 - 1/T_1)]$	$B_{25/50}$	-	3375	-	K

## Thermische Eigenschaften / thermal properties

Innerer Wärmewiderstand; DC thermal resistance, junction to case; DC	Transistor Wechsler. / transistor inverter	$R_{thJC}$	-	-	1,65	K/W
	Diode Wechselrichter / diode inverter		-	-	3,80	K/W
Wärmewiderstand; DC thermal resistance, junction to heat sink; DC	Transistor Wechsler. / transistor inverter	$R_{thJH}$	-	2,20	-	K/W
	Diode Wechselrichter / diode inverter		-	4,50	-	K/W
$\lambda_{\text{Paste}} = 1 \text{ W/m}^2\text{K} / \lambda_{\text{grease}} = 1 \text{ W/m}^2\text{K}$						
Übergangs-Wärmewiderstand; DC thermal resistance, case to heat sink; DC	Transistor Wechsler. / transistor inverter	$R_{thCH}$	-	0,70	-	K/W
	Diode Wechselrichter / diode inverter		-	1,00	-	K/W
$\lambda_{\text{Paste}} = 1 \text{ W/m}^2\text{K} / \lambda_{\text{grease}} = 1 \text{ W/m}^2\text{K}$						
Höchstzulässige Sperrschichttemp. maximum junction temperature		$T_{vjmax}$	-	-	150	$^\circ\text{C}$
Betriebstemperatur operation temperature		$T_{op}$	-40	-	125	$^\circ\text{C}$
Lagertemperatur storage temperature		$T_{stg}$	-40	-	125	$^\circ\text{C}$

## Mechanische Eigenschaften / mechanical properties

Innere Isolation internal insulation				$\text{Al}_2\text{O}_3$	
CTI comperative tracking index				225	
Anpresskraft pro Feder mounting force per clamp		F		20..50	N
Gewicht weight		G		25	g
Kriechstrecke creepage distance	Anschluss - Kühlkörper terminal to heat sink			10,5	mm
	Anschluss - Anschluss terminal to terminal			5	mm
Luftstrecke clearance distance	Anschluss - Kühlkörper terminal to heat sink			9	mm
	Anschluss - Anschluss terminal to terminal			5	mm

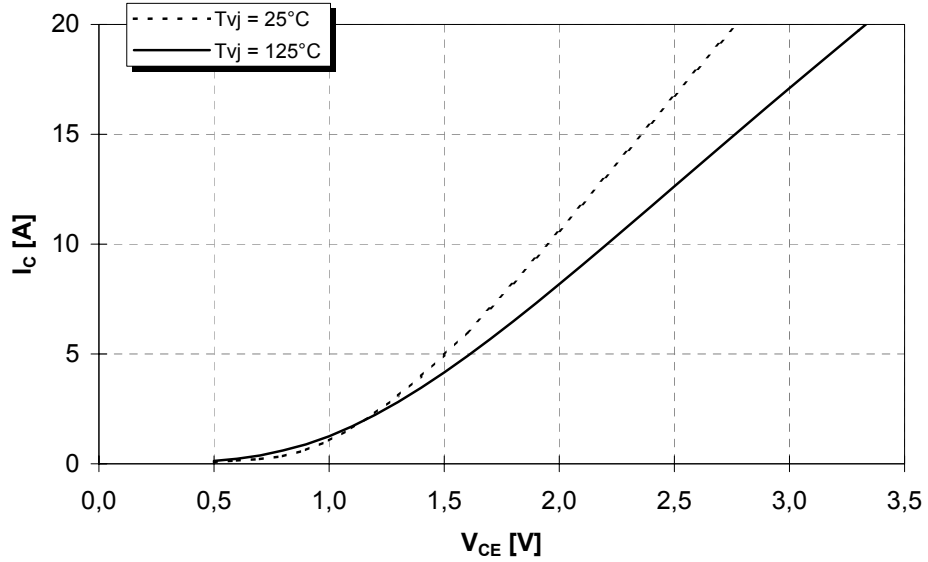


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**Ausgangskennlinie (typisch)**  
**output characteristic (typical)**

$I_C = f(V_{CE})$

$V_{GE} = 15V$

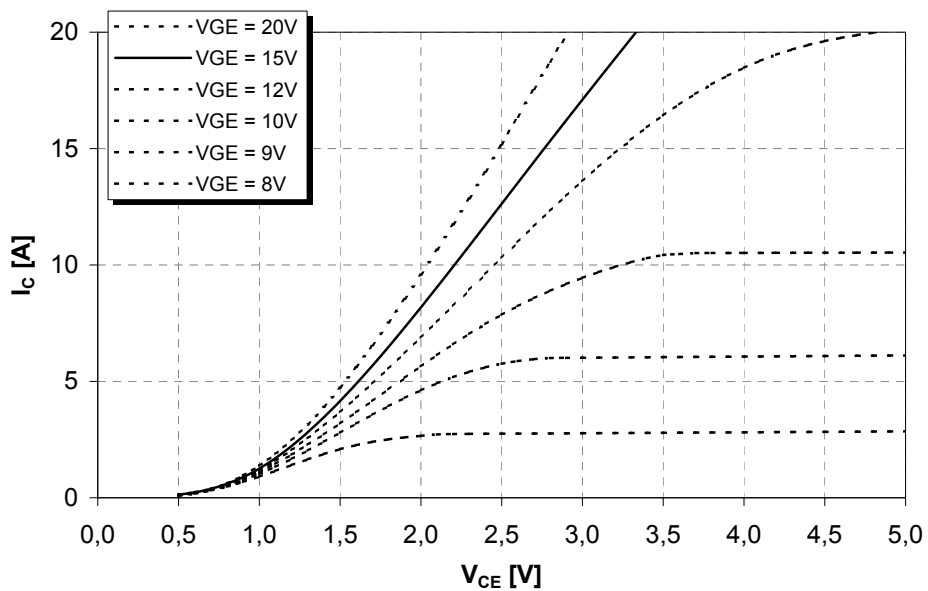


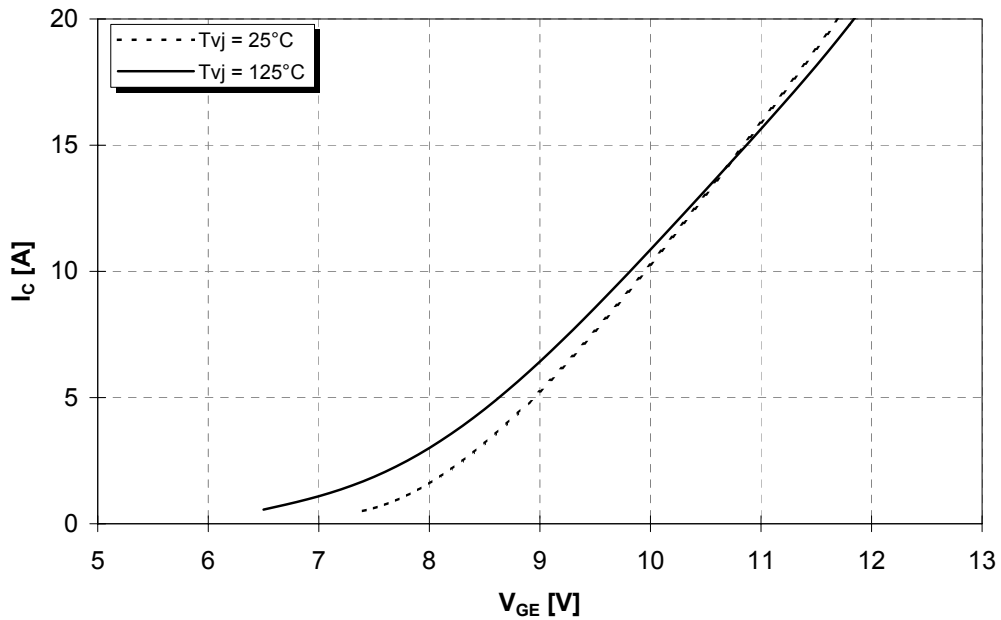
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**Ausgangskennlinienfeld (typisch)**  
**output characteristic (typical)**

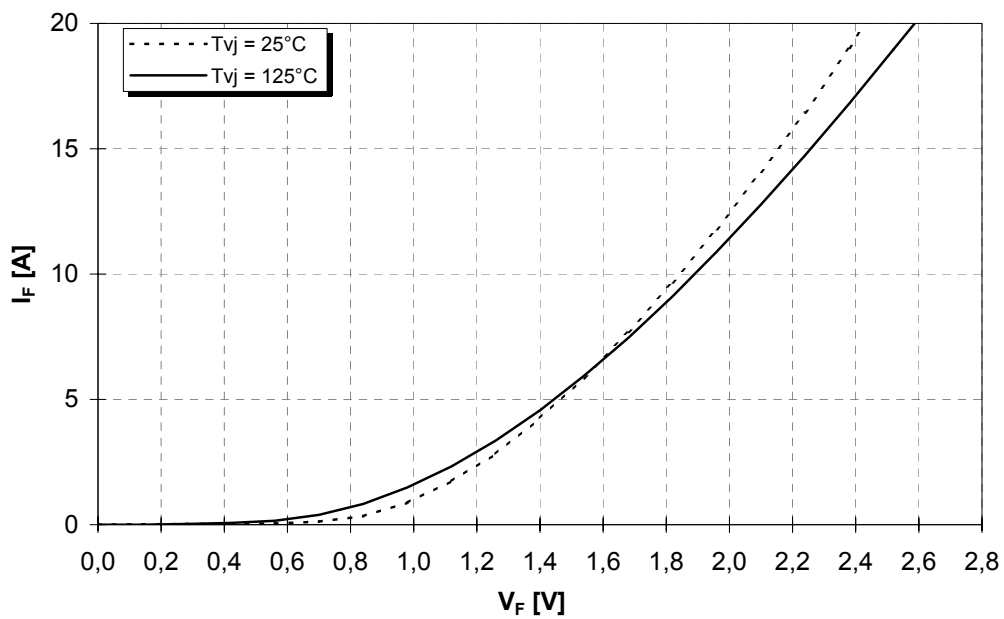
$I_C = f(V_{CE})$

$T_{vj} = 125^\circ C$



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transfer characteristic (typical) $I_C = f(V_{GE})$   
 $V_{CE} = 20V$ 

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Durchlasskennlinie der Inversdiode (typisch)  
forward characteristic of inverse diode (typical) $I_F = f(V_F)$ 

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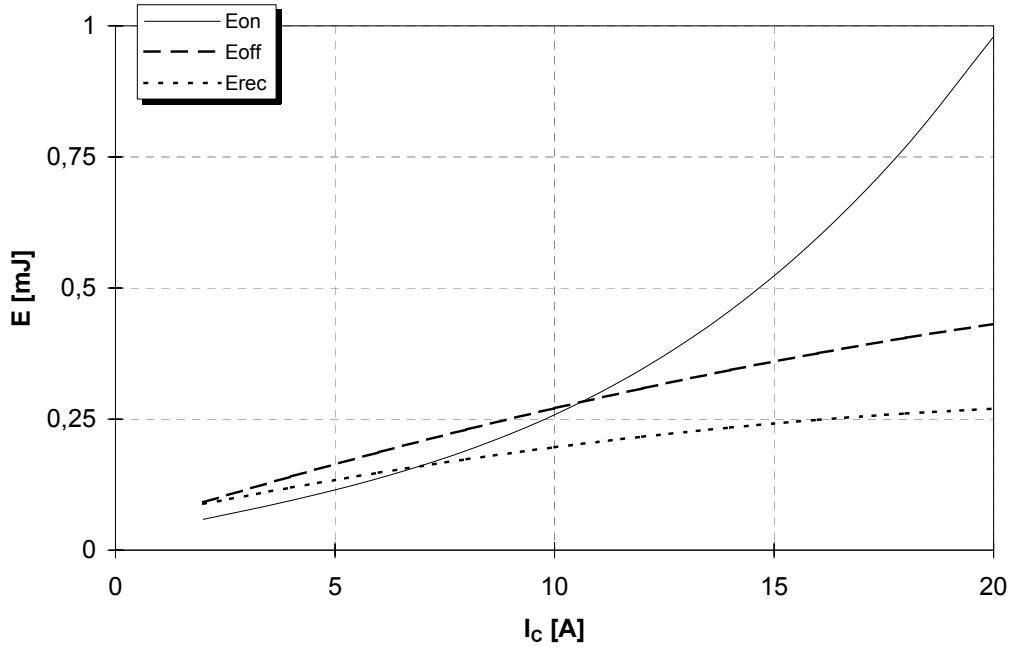
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### Schaltverluste (typisch) switching losses (typical)

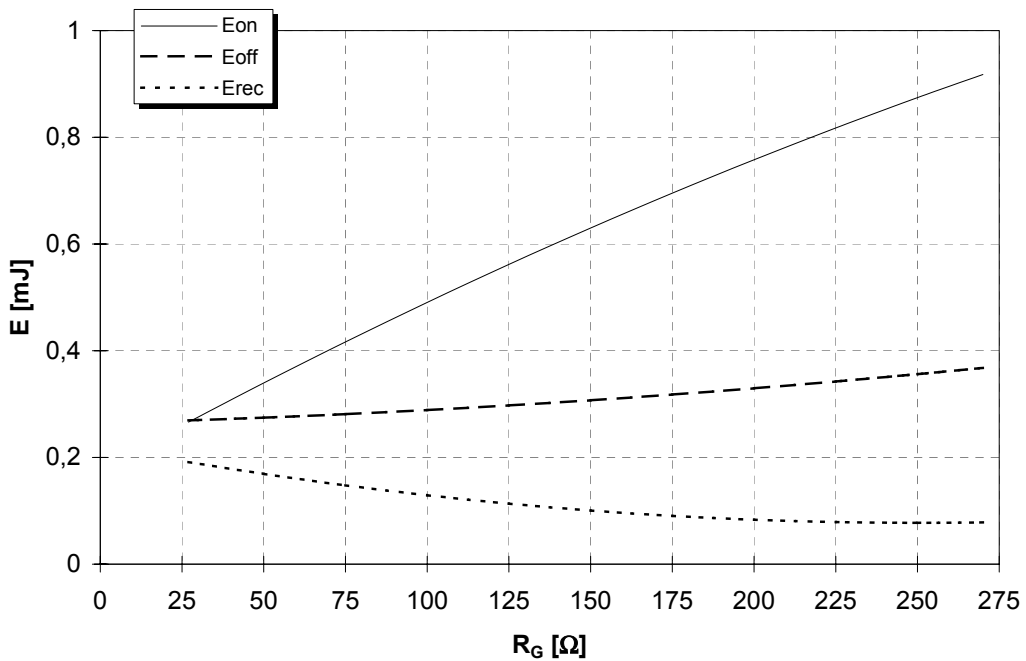
$E_{on} = f(I_C)$ ,  $E_{off} = f(I_C)$ ,  $E_{rec} = f(I_C)$   
 $V_{GE} = \pm 15V$ ,  $R_{Gon} = R_{Goff} = 27\Omega$ ,  $V_{CE} = 300V$ ,  $T_{vj} = 125^\circ C$



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### Schaltverluste (typisch) switching losses (typical)

$E_{on} = f(R_G)$ ,  $E_{off} = f(R_G)$ ,  $E_{rec} = f(R_G)$   
 $V_{GE} = \pm 15V$ ,  $I_C = 10A$ ,  $V_{CE} = 300V$ ,  $T_{vj} = 125^\circ C$

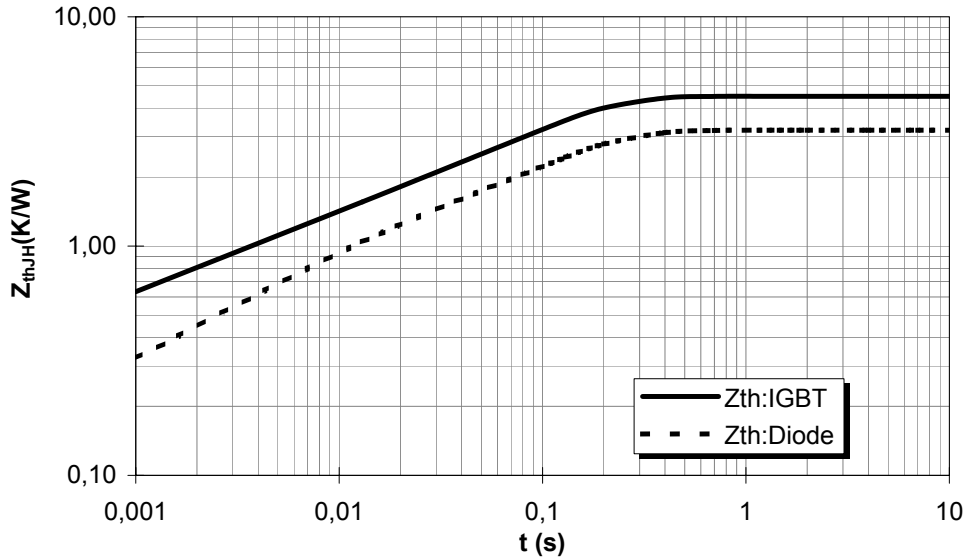




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Transienter Wärmewiderstand  
transient thermal impedance

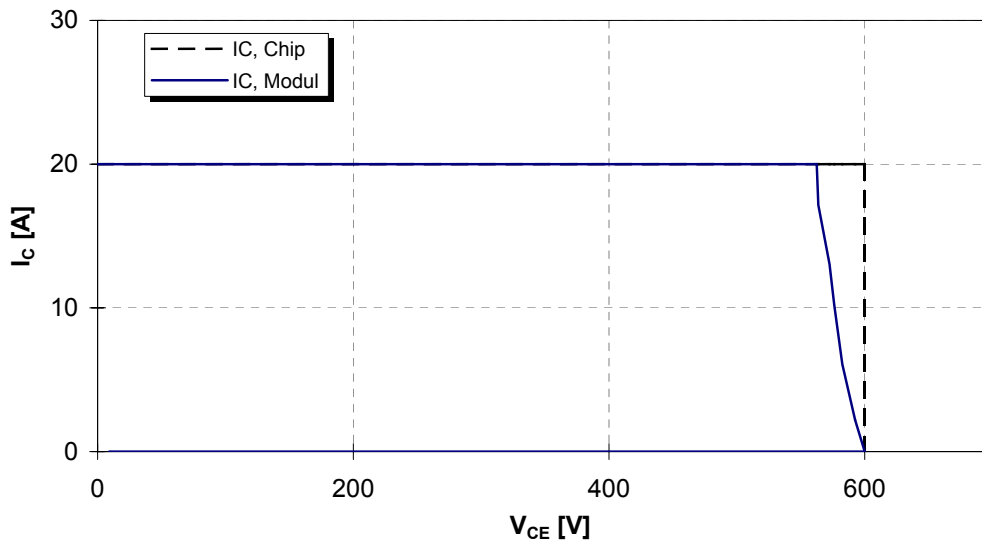
$$Z_{thJH} = f(t)$$



i	1	2	3	4
$r_i$ [K/kW]: IGBT	270,0	900,0	2520,0	810,0
$\tau_i$ [s]: IGBT	0,000232	0,00215	0,09946	0,12318
$r_i$ [K/kW]: Diode	192,0	640,0	1792,0	576,0
$\tau_i$ [s]: Diode	0,000307	0,00484	0,10644	0,14203

Sicherer Arbeitsbereich (RBSOA)  
reverse bias safe operation area (RBSOA)

$V_{GE}=15V, T_j=125^\circ C, R_G = 27 \Omega$



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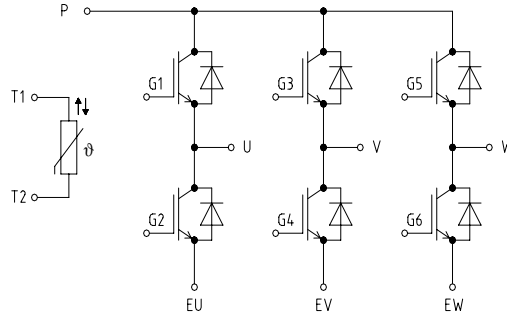
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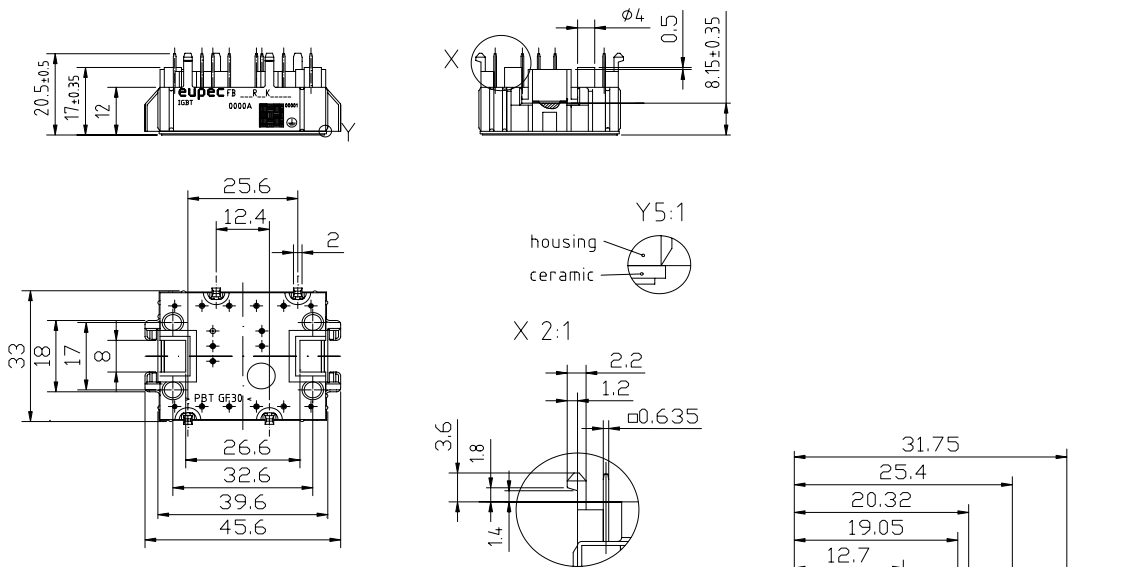


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### Schaltbild circuit diagram

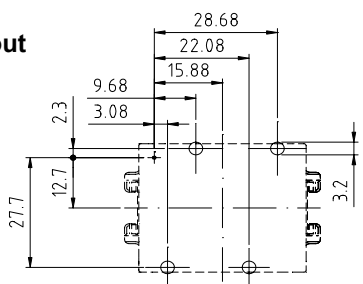


### Gehäusemaße package outline

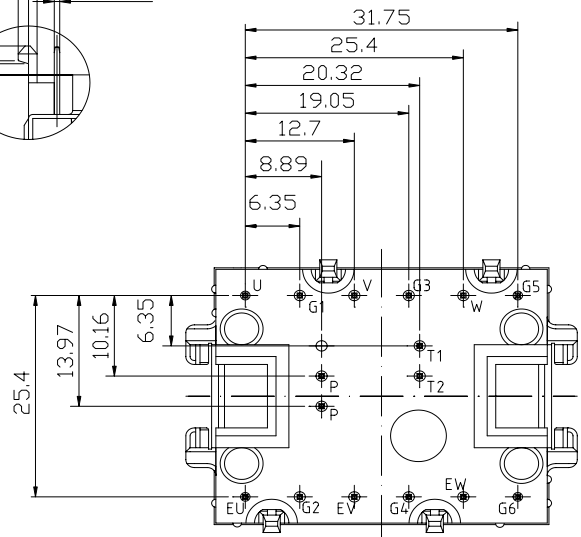


Module only designed for mounting on PCB with 1.6 ± 0.2 mm thickness

### Bohrplan drilling layout



Pinpositions with tolerance



Mit dieser technischen Information werden Halbleiterbauelemente spezifiziert, jedoch keine Eigenschaften zugesichert. Sie gilt in Verbindung mit den zugehörigen technischen Erläuterungen.

This technical information specifies semiconductor devices but promises no characteristics. It is valid with the belonging technical notes.